

# 562/564 Series

## Circuit Board Mount Blocks for TE5/TR5 Type Fuses



562 Series Holder

564 Series Holder

### Product Characteristics

	562 Series	564 Series
<b>Compatible Fuses</b>	TR5/TE5	
<b>Materials</b>	Block: Black Thermoplastic, UL94 V-0 PET Terminals: Copper alloy; solderable tinned	
<b>Electrical Data (23°C)</b>	Rated Voltage: 250V Max. Current/Power: 6.3A/1.6W	
<b>Mounting</b>	PC Board, 5.08mm pin spacing	PC Board, 5.08mm pad spacing
<b>Minimum Cross Section</b>	Conducting path - 0.1mm <sup>2</sup>	Conducting path - 0.1mm <sup>2</sup>
<b>Unit Weight</b>	0.12g	0.44g
<b>Ambient Temperature</b>	- 40°C to + 85°C	

### Ordering Information

Ordering Number	Circuit Board Mounting	Packaging
56200001009	Thru-Hole	1000 (Bulk pack)
56400001009	Surface Mount	1500 (Tape /Reel)

### Agency Approvals

Agency	Agency File Number	
	562 Series	564 Series
	E14721	E14721

### Additional Information



Resources  
562 Series



Accessories  
562 Series



Samples  
562 Series



Resources  
564 Series



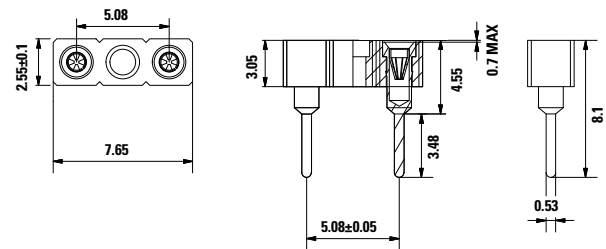
Accessories  
564 Series



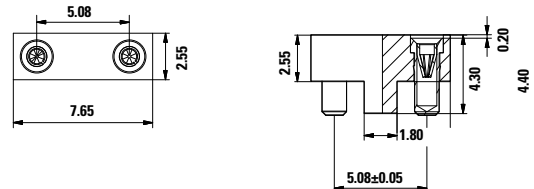
Samples  
564 Series

### Dimensions units in mm

#### 562 Series Holder



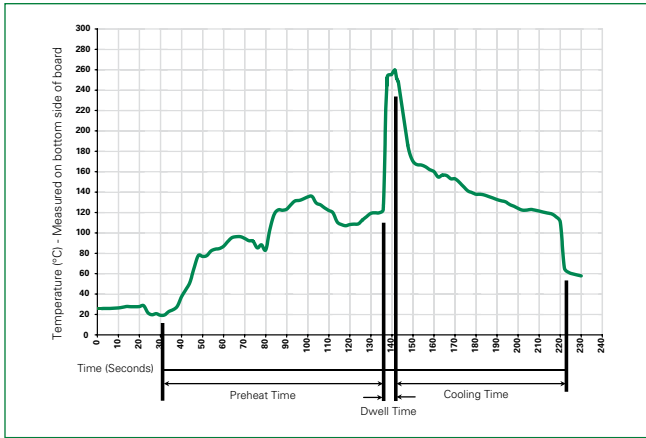
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### Soldering Parameters - Wave Soldering



#### Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

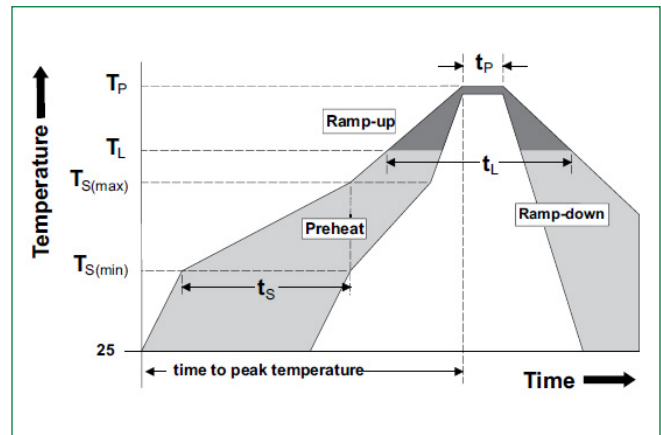
#### Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C  
 Heating time: 5 seconds max

**Note:** These devices are not recommended for IR and Convection Reflow process

### Soldering Parameters - Reflow Soldering

<b>Reflow Condition</b>	Pb - Free assembly	
<b>Number of allowed reflow cycles</b>	3	
<b>Pre Heat</b>	-Temperature Min ( $T_{s(min)}$ )	150°C
	-Temperature Max ( $T_{s(max)}$ )	200°C
	-Time (Min to Max) ( $t_p$ )	60 - 120 Secs.
<b>Average ramp up rate (Liquidus Temp (<math>T_L</math>) to peak)</b>	5°C/second max.	
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>	5°C/second max.	
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	-Temperature ( $t_l$ )	60 - 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>	240 +/- 5 °C	
<b>Time within 50C of actual peak Temperature (<math>t_p</math>)</b>	30 secs. max.	
<b>Ramp-down Rate</b>	5°C/second max.	
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>	8 minutes max.	
<b>Do not exceed</b>	245°C	



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